### ■ SPECIFICATION

Item			Non-latching FTR-C1 ( ) A	Latching FTR-C1 ( ) B		
Contact Data	Configuration		2 form C	2 form C		
	Construction		Bifurcated			
	Material	Material		Gold plated silver palladium (stationary contact)		
			Silver palladium (movable	Silver palladium (movable contact)		
	Resistance (Initial)		Max. 150mΩ at 1A, 6VDC			
	Contact rating resistive		1A, 30VDC / 0.3A, 125VAC			
	Max. Switching Voltage		250VAC / 220VDC			
	Max. Switching Power		62.5VA / 30W			
	Max. Carry Current		2A	2A		
	Min. Switching Load *		0.01mA, 10mVDC			
Life	Mechanical		Min. 10 x 10 <sup>6</sup> operations	Min. 10 x 10 <sup>6</sup> operations		
	Electrical (resistive)		Min. 100 x 10 <sup>3</sup> operations 1A, 30VD	Min. 100 x 10 <sup>3</sup> operations at 0.3A, 125VAC / 1A, 30VD		
Coil Data	Rated Power		280 to 300mW	140 to 180mW		
	Operate Power		158 to 162mW	158 to 162mW		
	Pulse width		-	Min. 20ms		
	Operating temp range		-40°C to +85°C (no frost)	-40°C to +85°C (no frost)		
	Storage temperature / humidity		-40°C to +85°C / 5% to 85% RH (no frost)			
Timing Data	Operate (at nominal voltage)		Max. 6ms (without bounce)			
	Release (at nominal voltage)		Max. 6ms (without bounce)			
Insulation	Resistance (Initial)		Min. 1,000MΩ at 500VDC			
	Dielectric strength	Open contacts	1,500VAC (50/60Hz) 1min			
		Adjacent contacts	1,500VAC (50/60Hz) 1mir	1,500VAC (50/60Hz) 1min		
		Contacts to coil	3,000VAC (50/60Hz) 1mir	3,000VAC (50/60Hz) 1min		
	Surge strength	Contacts to coil	5,000V, 2 x 10μs	5,000V, 2 x 10μs		
		Open contacts	0.6mm	0.6mm		
	Clearance	Adjacent contacts	1.0mm			
		Contacts to coil	2.0mm	2.0mm		
	Creepage	Open contacts	0.6mm			
		Adjacent contacts	1.0mm			
		Contacts to coil	2.5mm			
Other	Vibration Resistance	Misoperation>1us	10 to 55 to 10 Hz single amplitude 1.65mm			
		Endurance	10 to 55 to 10 Hz single amplitude 2.5mm			
	Shock	Misoperation>1us	Min. 500m/s <sup>2</sup> (11+/-1ms)			
	SHUCK	Endurance	Min. 1,000m/s <sup>2</sup> (6+/-1ms)			
	Weight		Approximately 2g			
	Sealing		RT III (plastic sealed)	RT III (plastic sealed)		

<sup>\*</sup> Minimujm switching loads mentioned above are reference values. Please perform the confirmation test with actual load before production since reference values may vary according to switching frequencies, environmental conditions and expected reliability levels.

### **COIL RATING**

### Standard type

Coil Code	Rated Coil Voltage (VDC)	Coil Resistance +/- 10% (Ohm)	Must Operate Voltage (VDC) *	Must Release Voltage (VDC) *	Nominal Coil Power (mW)
003	3	32.1	2.25	0.3	
4.5	4.5	72.3	3.38	0.45	280
005	5	89.3	3.75	0.5	
012	12	514	9	1.2	
024	24	1,920	18	2.4	300

### Latching type

Coil Code	Rated Coil Voltage (VDC)	Coil Resistance +/- 10% (Ohm)	Set Voltage (VDC) *	Reset Voltage (VDC) *	Nominal Coil Power (mW)
003	3	64.0	+2.25	- 2.25	
4.5	4.5	145	+3.38	- 3.38	140
005	5	179	+3.75	- 3.75	140
012	12	1,029	+9	- 9	
024	24	3,200	+18	- 18	180

Note: All values in the table are valid for 20°C and zero contact current.

\* Specified operate values are valid for pulse wave voltage.

Note: Please use at rated coil voltage. Please perform the confirmation test with actual conditions.

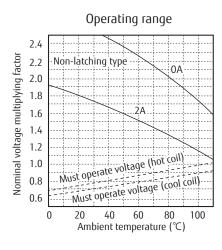
### **SAFETY STANDARDS**

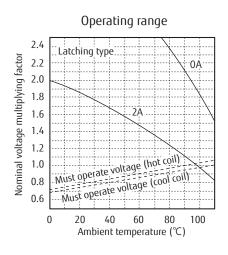
Туре	Compliance	Contact rating
UL	UL 508	Flammability: UL 94-V0 (plastics)
	E63615	0.3A, 125 VAC (general use) (UL) 0.5A, 125VAC (CSA)
CSA	C22.2 No. 14 LR 40304	2A, 30VDC (general use) 0.3A, 110VDC (general use)

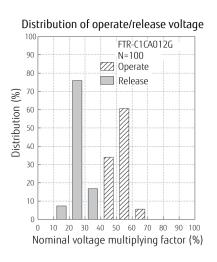
Comply with Telcordia specifications and meet BSI Marking only for UL, CSA

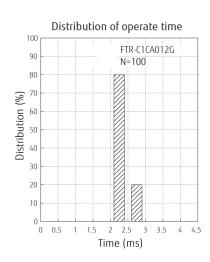
3

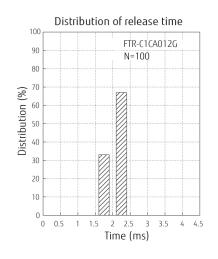
#### ■ CHARACTERISTIC DATA

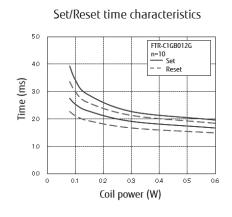


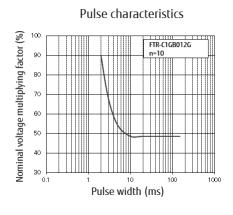


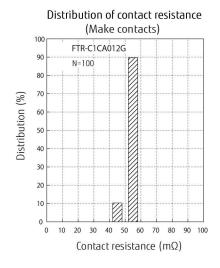


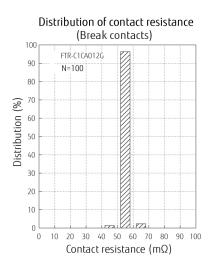


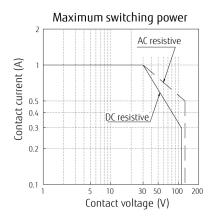


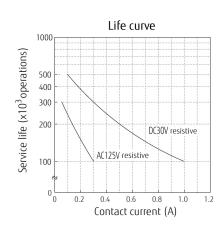












### DIMENSIONS

### Through hole type Schematics Recommended PCB layout Dimensions (BOTTOM VIEW) (BOTTOM VIEW) 15.2 max. 7.7 max 8-φ1 14.9 typ. 7.4 typ. 9.1 typ. 9.4 max 5.08 Orientation mark 0.2 Surface mount type Schematics Recommended PCB layout Dimensions (TOP VIEW) (TOP VIEW) 7.7 max. 7.4 typ. 15.2 max 14.9 typ. 9.7 max. 9.4 typ. 5.08 5.08 9.4 Orientation mark Surface mount (space saving) type Recommended PCB layout Schematics Dimensions (TOP VIEW) (TOP VIEW) 15.2 max 7.7 max. 14.9 typ. 7.4 typ. 10 8 5.08 2.54 2.54 5.08 Orientation mark 7.4

Note: (...): dimensions are reference

Note: Dimensions of the terminals do not include thickness of pre-solder.

Note: Dimensions do not include tolerances. Please ask specification in case you need tolerances.

Note: Tolerance of PCB layout: ±0.1 unless otherwise specified.

Unit: mm

#### ■ RECOMMENDED SOLDERING CONDITIONS SMT

### (TEMPERATURE PROFILE, please see page 9)

Note: 1.Temperature profiles show the temperature of PC board surface.

2. Please perform soldering test with your actual PC board before mass production, since the temperatures of PC board surfaces vary according to the size of PC board, status of parts mounting and heating method.

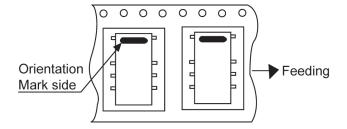
### ■ TAPE & REEL PACKAGING SPECIFICATION

1. Taping standards: JIS C 0806 and

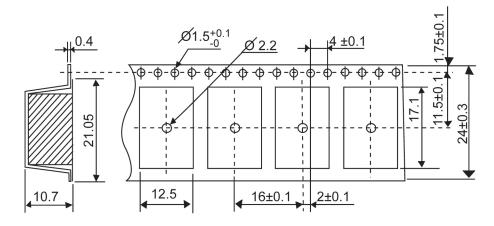
RC-10092B (EIAJ)

2. Tape type: TB2416 or TE2416

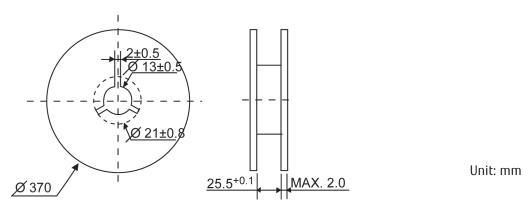
3. Reel type: RD24D 4. Quantity of 1 reel: 500 pieces



Tape Dimensions:



Reel Dimensions:



# **RoHS Compliance and Lead Free Information**

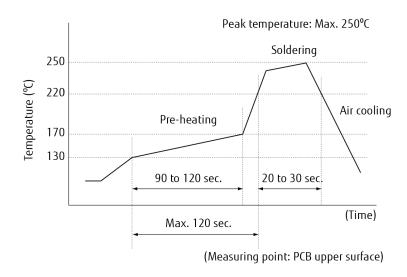
### 1. General Information

- All relays produced by Fujitsu Components are compliant with RoHS directive 2011/65/EU including amendments.
- Cadmium as used in electrical contacts is exempted from the RoHS directives.
   As per Annex III of directive 2011/65/EU.
- All relays are lead-free. Please refer to Lead-Free Status Info for older date codes at: http://www.fujitsu.com/downloads/MICRO/fcai/relays/lead-free-letter.pdf
- Lead free solder plating on relay terminals is Sn-3.0Ag-0.5Cu, unless otherwise specified. This material has been verified to be compatible with PbSn assembly process.
- Characteristic data is not guaranteed values but measured values of samples from production line.

### 2. Recommended Lead Free Solder Condition

• Recommended solder Sn-3.0Ag-0.5Cu.

Reflow Solder condition for SMT



#### Flow Solder Condition:

Pre-heating: maximum 120°C

within 90 sec.

Soldering: dip within 5 sec. at

255°C ± 5°C solder bath

Relay must be cooled by air immediately

after soldering

### Solder by Soldering Iron:

Soldering Iron 30-60W

Temperature: maximum 340-360°C maximum 3 sec.

#### **REFLOW**

Note:

- 1.Temperature profiles show the temperature of PC board surface.
- 2. Please perform soldering test with your actual PC board before mass production, since the temperatures of PC board surfaces can vary, depending on the size of PC board, status of partsmounting and heating method.

# We highly recommend that you confirm your actual solder conditions

# 3. Moisture Sensitivity

- SMT versions of FTR-C1 relays in Tape & Reel package will be shipped in Moisture Barrier Bag(MBB).
- Moisture Sensitivity Level (MSL) of FTR-C1 relay is indicated on the packing caution label.
- Relays must be stored in the unopened MBB at storage conditions <40C/90%RH for a maximum 1 year</li>
- SMT versions of FTR-C1 relays in tube packing will not be shipped in MBB. Therefore, these relays shall be dried by baking before reflow soldering process according to IPC/JEDEC J-STD-033.

### 4. Tin Whiskers

• Dipped SnAgCu solder is known as presenting a low risk to tin whisker development. No considerable length whisker was found by our in house test.

### **Cautions**

- All values mentioned in this datasheet are provided under ideal conditions. Please perform the confirmation test before actual use.
- Do not use relays in the atmosphere with sulfide gas, chloride gas or nitric oxide. Contact resistance may increase.
- Do not use silicon or silicon-containing product or materials near relays. It may cause contact failure.

# Notes for latching relay

- Latching relays are shipped in the state set, but state may change due to shock during transportation or mounting. Before using the relays, it is advisable to bring the relays in necessary state (set or reset) and program a circuit sequence. Otherwise, it will or will not operate simultaneously with power activation.
- Please connect relay coils according to specified polarity.
- Do not apply voltage to both set coil and reset coil at a time.

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